These assemblies are ESD sensitive. ESD precautions shall be observed.
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Components marked 'DNP' should not be populated, and may not be in bill of materials.

Assembly Variant: [No Variations]

PCB Viewed from Top Side | Board #: PMP6659 | REV: B | Sun REV: Not In Version Control
---|---|---|---
Ignore | Top Overlay

Plot Name = Top Assembly Drawing | Generated: 1/9/2014 4:18:52 PM | Texas Instruments
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: [No Variations]

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP6659</th>
<th>REV: B</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TEXAS INSTRUMENTS</td>
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